

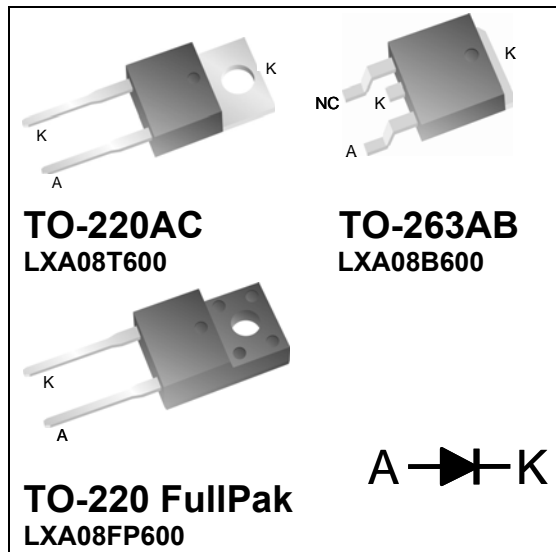
LXA08T600, LXA08B600, LXA08FP600 Qspeed™ Family

600 V, 8 A X-Series PFC Diode

Product Summary

$I_{F(AVG)}$	8	A
V_{RRM}	600	V
Q_{RR} (Typ at 125 °C)	82	nC
I_{RRM} (Typ at 125 °C)	3.5	A
Softness t_b/t_a (Typ at 125 °C)	0.55	

Pin Assignment



General Description

This device has the lowest Q_{RR} of any 600V Silicon diode. Its recovery characteristics increase efficiency, reduce EMI and eliminate snubbers.

Applications

- Power Factor Correction (PFC) Boost Diode
- Motor drive circuits
- DC-AC Inverters

Features

- Low Q_{RR} , Low I_{RRM} , Low t_{RR}
- High di_F/dt capable (1000A/ μ s)
- Soft recovery
- FullPak Insulation = 2500V_{RMS}

Benefits

- Increases efficiency
- Eliminates need for snubber circuits
- Reduces EMI filter component size & count
- Enables extremely fast switching

RoHS Compliant

Package uses Lead-free plating and Green mold compound.

Halogen free per IEC 61249-2-21.

Absolute Maximum Ratings

Absolute maximum ratings are the values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Symbol	Parameter	Conditions	Rating	Units
V_{RRM}	Peak repetitive reverse voltage		600	V
$I_{F(AVG)}$	Average forward current	$T_J = 150\text{ °C}, T_C = 122\text{ °C}$ (220AC, 263AB)	8	A
		$T_J = 150\text{ °C}, T_C = 81\text{ °C}$. (FullPak)		
I_{FSM}	Non-repetitive peak surge current	60 Hz, ½ cycle	60	A
I_{FSM}	Non-repetitive peak surge current	½ cycle of $t=28\text{ }\mu$ s Sinusoid, $T_C=25\text{ °C}$	350	A
$T_{J(MAX)}$	Maximum junction temperature		150	°C
T_{STG}	Storage temperature		-55 to 150	°C
	Lead soldering temperature	Leads at 1.6 mm from case, 10 sec	300	°C
P_D	Power dissipation	$T_C = 25\text{ °C}$. (220AC, 263AB)	83	W
		$T_C = 25\text{ °C}$. (FullPak)	34	W

Thermal Resistance

Symbol	Resistance from:	Conditions	Rating	Units
$R_{\theta JA}$	Junction to ambient	TO-220AC (Only)	62	°C/W
$R_{\theta JC}$	Junction to case	TO-220AC, TO-263AB	1.5	°C/W
		TO-220AC FullPak	3.7	°C/W

Electrical Specifications at $T_J = 25\text{ }^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
DC Characteristics							
I_R	Reverse current	$V_R = 600\text{V}, T_J = 25\text{ }^\circ\text{C}$	-	-	250	μA	
		$V_R = 600\text{V}, T_J = 125\text{ }^\circ\text{C}$	-	0.85	-	mA	
V_F	Forward voltage	$I_F = 8\text{A}, T_J = 25\text{ }^\circ\text{C}$	-	2.35	2.94	V	
		$I_F = 8\text{A}, T_J = 150\text{ }^\circ\text{C}$	-	2.1	-	V	
C_J	Junction capacitance	$V_R = 10\text{V}, 1\text{ MHz}$	-	40	-	pF	
Dynamic Characteristics							
t_{RR}	Reverse recovery time	$di/dt = 200\text{ A}/\mu\text{s}$ $V_R = 400\text{V}, I_F = 8\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	-	21.5	34	ns
			$T_J = 125\text{ }^\circ\text{C}$	-	33	53 ⁽¹⁾	ns
Q_{RR}	Reverse recovery charge	$di/dt = 200\text{ A}/\mu\text{s}$ $V_R = 400\text{V}, I_F = 8\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	-	31	48	nC
			$T_J = 125\text{ }^\circ\text{C}$	-	82	130 ⁽¹⁾	nC
I_{RRM}	Maximum reverse recovery current	$di/dt = 200\text{ A}/\mu\text{s}$ $V_R = 400\text{V}, I_F = 8\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	-	2.2	2.8	A
			$T_J = 125\text{ }^\circ\text{C}$	-	3.5	4.5 ⁽¹⁾	A
S	Softness factor = $\frac{t_b}{t_a}$	$di/dt = 200\text{ A}/\mu\text{s}$ $V_R = 400\text{V}, I_F = 8\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	-	0.74	-	
			$T_J = 125\text{ }^\circ\text{C}$	-	0.55	-	

Note to component engineers: X-Series diodes employ Schottky technologies in their design and construction. Therefore, Component Engineers should plan their test setups to be similar to those for traditional Schottky test setups. (For additional details, see Application Note AN-300.)

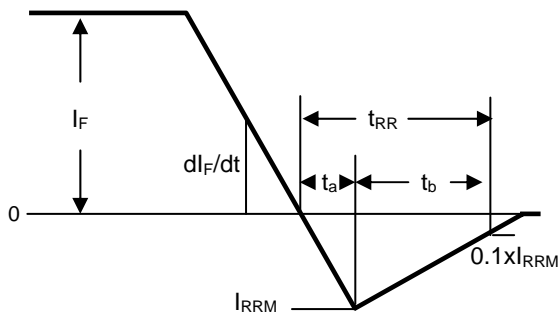


Figure 1. Reverse Recovery Definitions

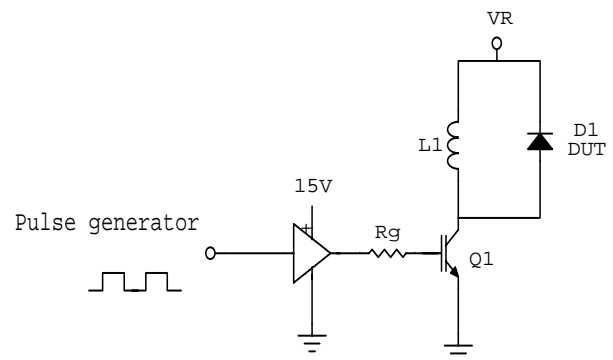


Figure 2. Reverse Recovery Test Circuit

Electrical Specifications at $T_J = 25\text{ }^\circ\text{C}$ (unless otherwise specified)

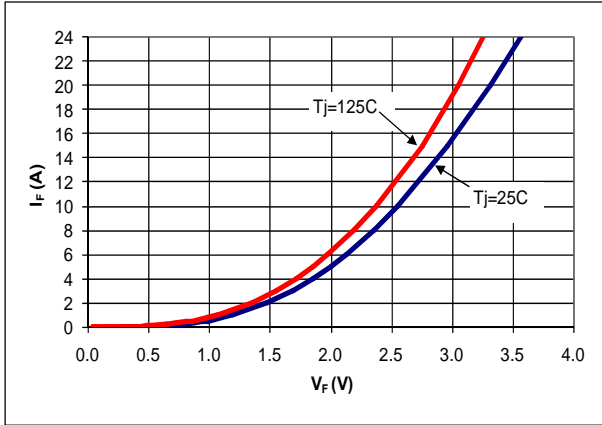


Figure 3. Typical I_F vs V_F

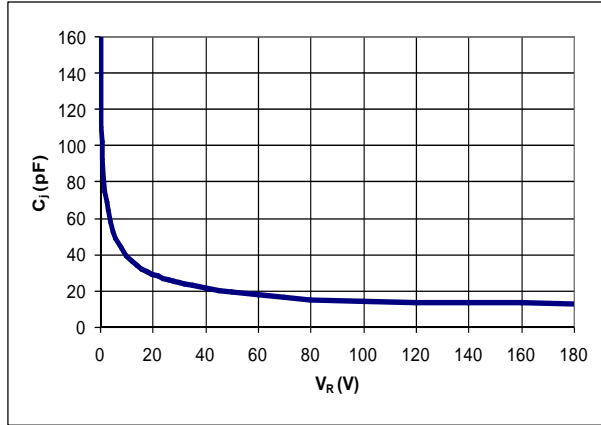


Figure 4. Typical C_i vs V_R

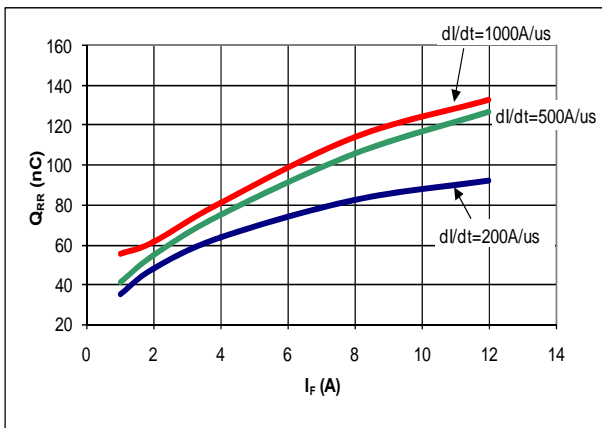


Figure 5. Typical Q_{RR} vs I_F at $T_J = 125\text{ }^\circ\text{C}$

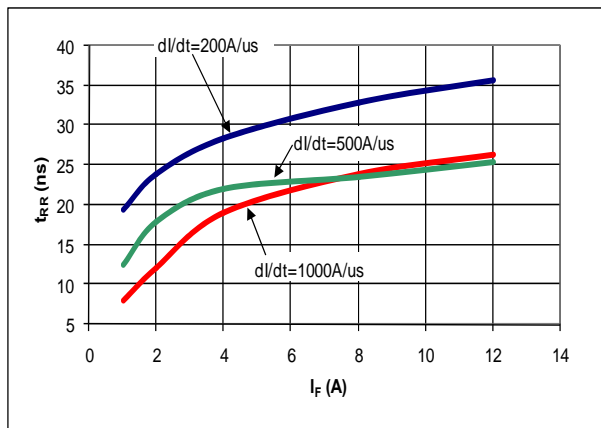


Figure 6. Typical t_{RR} vs I_F at $T_J = 125\text{ }^\circ\text{C}$

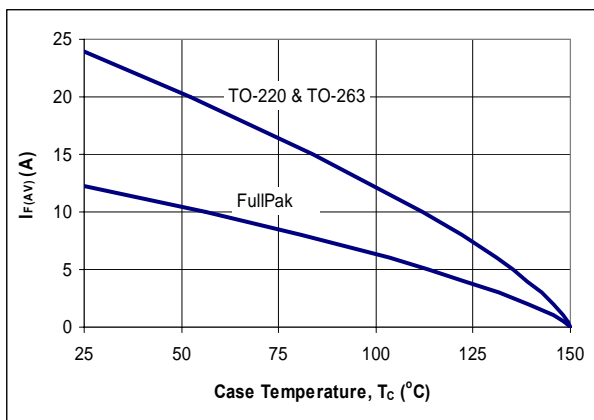


Figure 7. DC Current Derating Curve

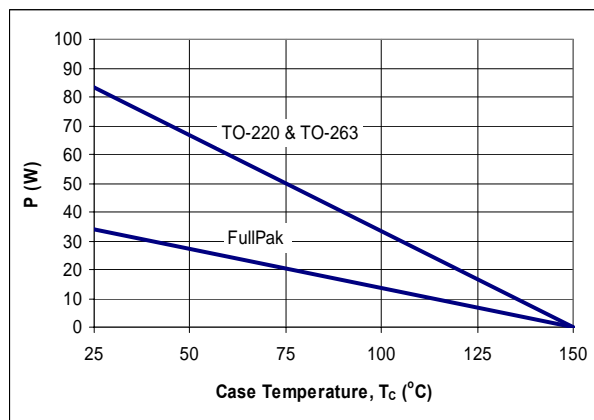


Figure 8. Power Derating Curve

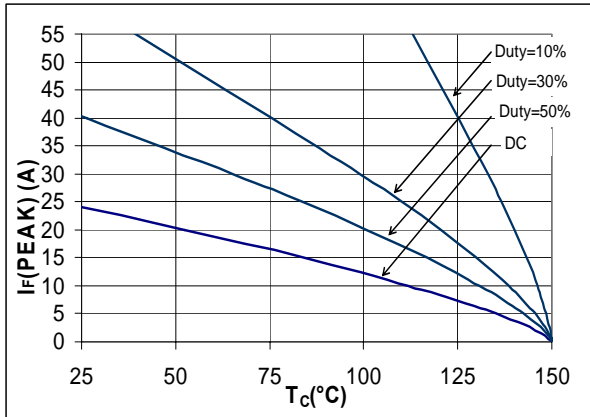


Figure 9. $I_f(\text{PEAK})$ vs T_c , $f=70$ kHz, TO-220 and TO-263

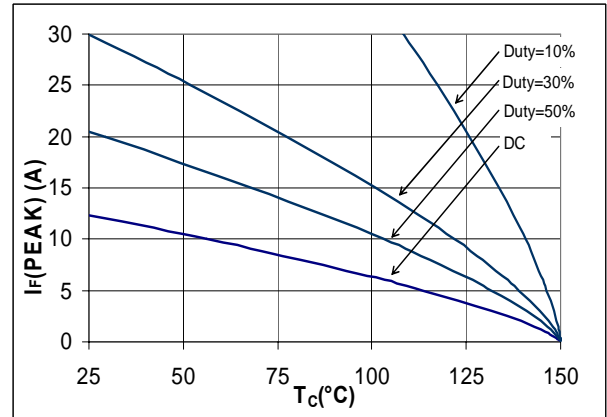


Figure 10. $I_f(\text{PEAK})$ vs T_c , $f=70$ kHz, FullPak

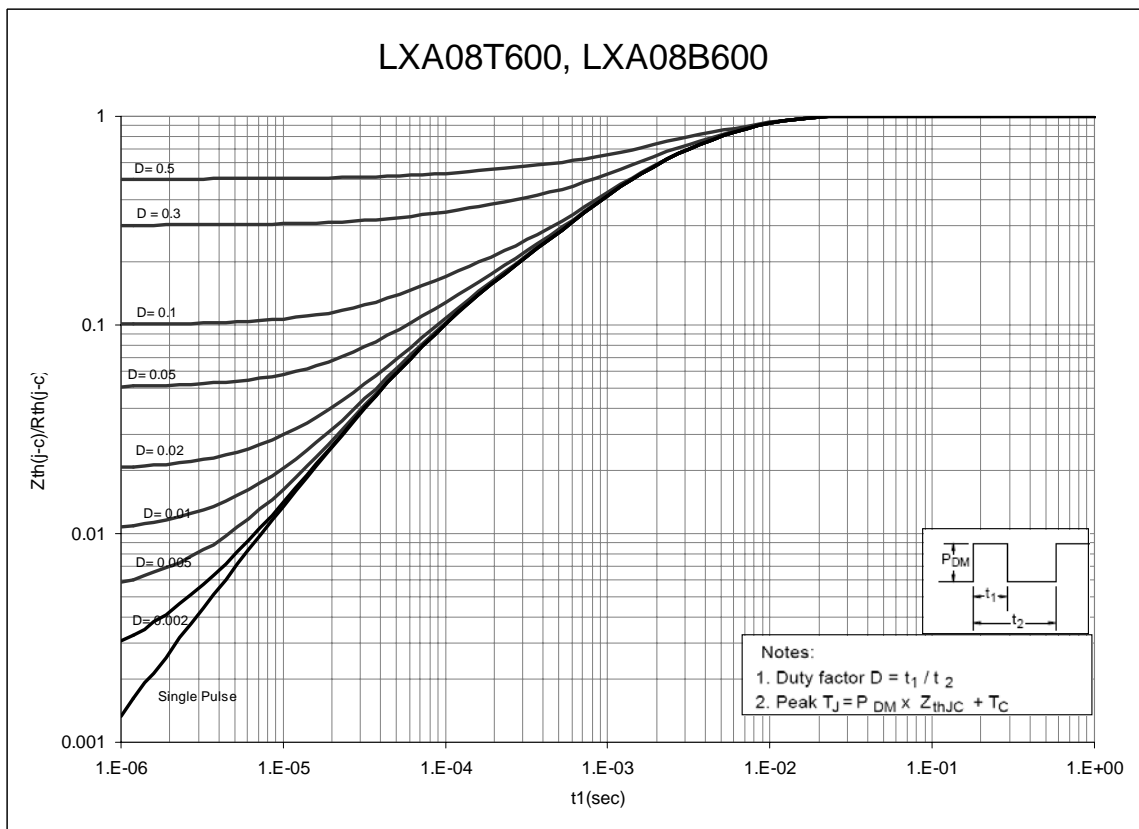


Figure 11. Normalized Maximum Transient Thermal Impedance, TO-220 and TO-263

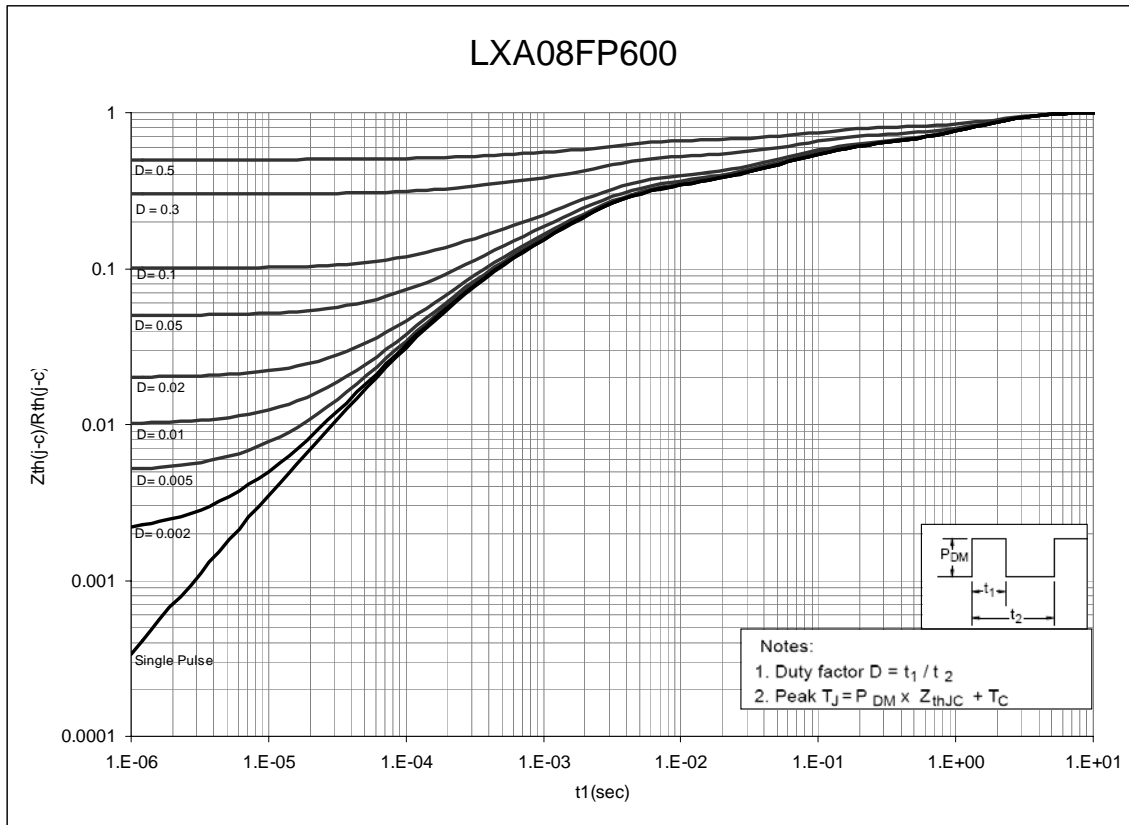
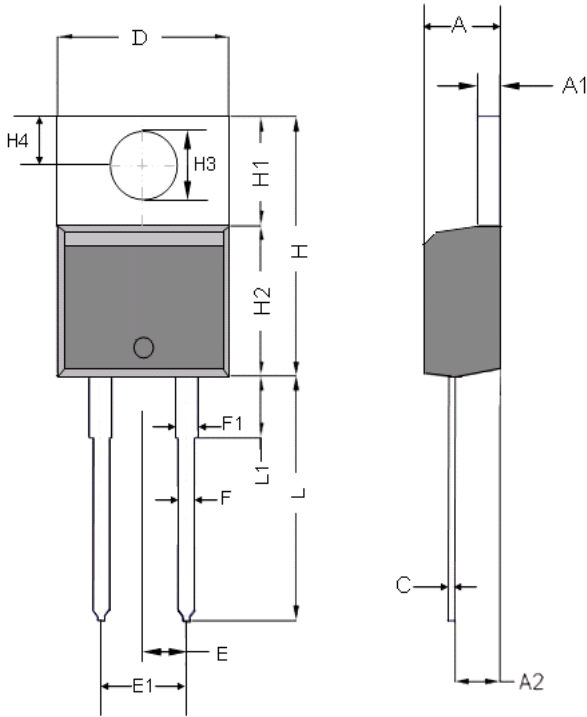


Figure 12. Normalized Maximum Transient Thermal Impedance, FullPak

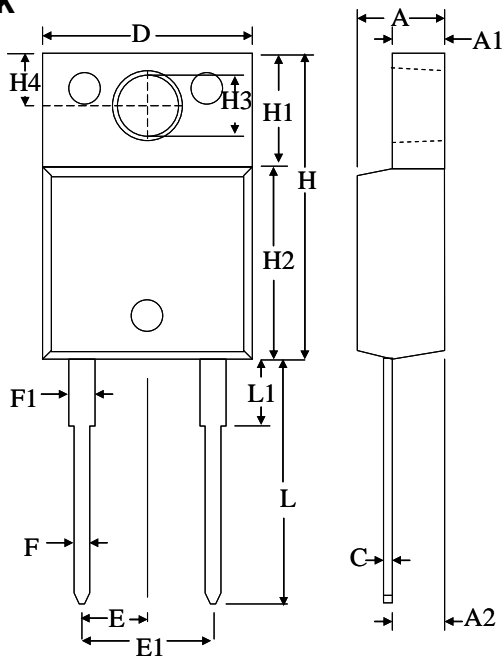
Dimensional Outline Drawings

TO-220AC



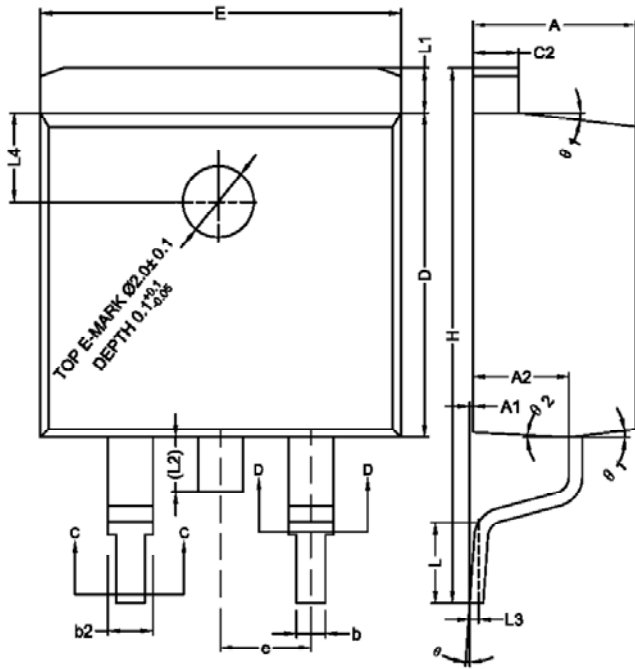
Dim	Millimeters	
	MIN	MAX
A	4.32	4.70
A1	1.14	1.40
A2	2.03	2.79
C	0.34	0.610
D	9.65	10.67
E	2.49	2.59
E1	4.98	5.18
F	0.508	1.016
F1	1.14	1.78
H	14.71	16.51
H1	5.84	6.55
H2	8.51	9.25
H3	3.53	3.96
H4	2.54	3.05
L	12.70	14.22
L1	-	6.35

FullPak



Dim	Millimeters	
	MIN	MAX
A	4.54	4.80
A1	2.57	2.83
A2	2.51	2.62
C	0.42	0.58
D	10.25	10.72
E	2.54 (BSC)	
E1	5.08 (BSC)	
F	0.624	0.776
F1	1.10	1.65
H	15.86	16.12
H1	6.06	6.56
H2	9.55	9.81
H3	2.95	3.05
H4	3.15	3.25
L	13.33	14.18
L1	3.18	3.43

TO-263AB



Dim	Millimeters	
	MIN	MAX
A	4.40	4.70
A1	0.00	0.25
A2	2.59	2.79
b	0.77	0.90
b2	1.23	1.36
c2	1.22	1.32
D	9.05	9.25
E	10.06	10.26
e	2.54 BSC	2.54 BSC
H	14.70	15.50
L	2.00	2.60
L1	1.17	1.40
L2	–	1.75
L3	0.25 BSC	0.25 BSC
L4	2.00 BSC	2.00 BSC
Θ	0°	8°
Θ1	5°	9°
Θ2	1°	5°

Mechanical Mounting Method	Maximum Torque / Pressure specification
Screw through hole in package tab	1 Newton Meter (nm) or 8.8 inch-pounds (lb-in)
Clamp against package body	12.3 kilogram-force per square centimeter (kgf/cm ²) or 175 lbf/in ²

Soldering time and temperature: This product has been designed for use with high-temperature, lead-free solder. The component leads can be subjected to a maximum temperature of 300 °C, for up to 10 seconds. See Application Note AN-303, for more details.

Ordering Information

Part Number	Package	Packing
LXA08T600, LXA08FP600	TO-220AC, FullPak	50 units/tube
LXA08B600	TO-263AB	800 units/reel

The information contained in this document is subject to change without notice.

Revision	Notes	Date
1.9	Released by Qspeed	06/10
1.10	Converted to Power Integrations Document	01/11

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